

09/915658

Class	Subclass
ISSUE CLASSIFICATION	

2002-0043

UTILITY SERIAL NUMBER	PATENT DATE	PATENT NUMBER
SERIAL NUMBER	FILING DATE	CLASS
09/915658	02/21/97	2814
SUBCLASS		EXAMINER

APPLICANTS  
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\*\*\*\*\*CONTINUING DATA\*\*\*\*\*  
VERIFIED

\*\*\*\*\*FOREIGN/PCT APPLICATIONS\*\*\*\*\*  
VERIFIED

FOREIGN FILING LICENSE GRANTED 01/08/97

Foreign priority claimed 35 USC 119 conditions met	<input type="checkbox"/> yes <input checked="" type="checkbox"/> no	AS FILED	STATE OR COUNTRY	SHEETS DRWGS.	TOTAL CLAIMS	INDEP. CLAIMS	FILING FEE RECEIVED	ATTORNEY'S DOCKET NO.
Verified and Acknowledged	Examiner's Initials		10	7	10	10	\$2,000.00	00002496
ADDRESS KILLWORTH BOUTMAN HARRIS & SCHREFF ONE DAYTON CENTRE SUITE 500 ONE SOUTH MAIN STREET DAYTON OH 45402-2023								
TITLE LOW RESISTANCE METAL SOLDER DIE ATTACH INTERCONNECTS AND METHOD OF MAKING								

U.S. DEPT. OF COMM. / PAT. &amp; TM—PTO-436L (Rev.12-94)

PARTS OF APPLICATION FILED SEPARATELY		Applications Examiner	
NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.
		Print Fig.	
Label Area		ISSUE BATCH NUMBER	
		PREPARED FOR ISSUE	
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